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Comparative Assessment of Crystalline-Silicon PV Technologies (PERC, TOPCon, HJT, IBC): Encapsulant Selection, Reliability Testing (PID, DH, UVID, LeTID, Hot-Spot, TC, HF), and Cost-Efficiency Trade-offs

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Abstract

We present a comparative study of four crystalline-silicon photovoltaic (PV) cell architectures—PERC, TOPCon, HJT, and IBC—integrating module-level performance ranges, manufacturing cost orientation, and reliability testing aligned with IEC standards. We analyze efficiency (20.5–24.5%), temperature coefficients, bifaciality, and indicative \$/W costs, and propose a bill-of-materials (BOM) decision framework using encapsulants EVA, EPE, and POE for glass-glass (GG) and glass-backsheet (GB) packages. We include a standardized test matrix for PID (IEC TS 62804-1), Damp Heat (DH), UV preconditioning (UVID), LeTID (IEC TS 63342), Hot-Spot endurance, Thermal Cycling (TC), and Humidity Freeze (HF). Charts compare efficiency, cost, LCOE, and retained-power trajectories for GG vs GB. Results indicate TOPCon as the near-term cost-performance default, HJT as a premium option in heat- and space-constrained contexts, and IBC as the high-efficiency frontier; encapsulant choice (POE/EPE) materially reduces PID and moisture-driven risks, especially in GG bifacial modules.

Keywords: TOPCon; PERC; HJT; IBC; Encapsulant; EVA; POE; EPE; PID; LeTID; IEC 61215; Reliability; LCOE; Bifacial; Glass-Glass; Glass-Backsheet

1. Introduction

Crystalline-silicon (c-Si) technologies dominate PV, with module efficiency advancing beyond 22% and N-type architectures displacing legacy PERC. Contemporary adoption centers on TOPCon, HJT, and back-contact (IBC), each with distinct process and reliability considerations. This report consolidates public data (2024–2026) and IEC-aligned test methods to guide material selection and qualification in hot/humid climates.

2. Methods

Performance ranges were synthesized from industry technology guides and trend reports. Cost orientation reflects directional \$/W ranges observed in China-centric manufacturing. Reliability test parameters follow

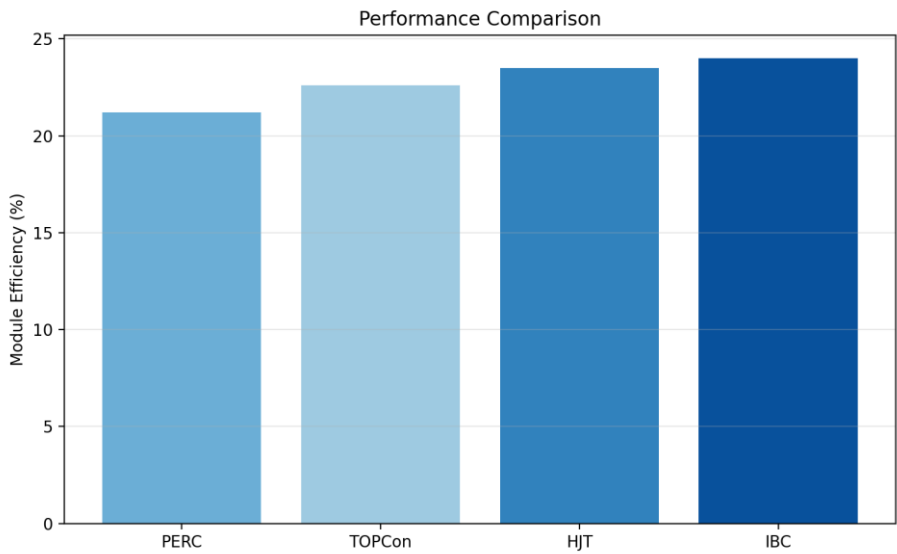
IEC 61215 and IEC TS 62804-1/IEC TS 63342. LCOE and retained-power charts were computed under hot-site assumptions; efficiency and cost charts use reported ranges.

3. Technology Overview

PERC: mature, low cost, higher LID/LeTID susceptibility. TOPCon: tunnel oxide passivated contacts, higher efficiency and bifaciality, reliable field behavior. HJT: heterojunction stacks, lowest temperature coefficients, high bifaciality, BOM-dependent reliability. IBC: rear contacts eliminate shading; premium process complexity.

4. Performance and Cost

Module efficiency ranges: PERC ~20.5–22%; TOPCon ~21.5–23.8%; HJT ~23–24%; IBC ~23–24.5%. Temperature coefficients: PERC -0.34 to -0.40%/°C; TOPCon -0.30 to -0.32%/°C; HJT ~-0.25%/°C typical. Bifaciality: PERC ~70%, TOPCon 80–90%, HJT up to ~95%. Indicative \$/W ordering: PERC < TOPCon < HJT < IBC.



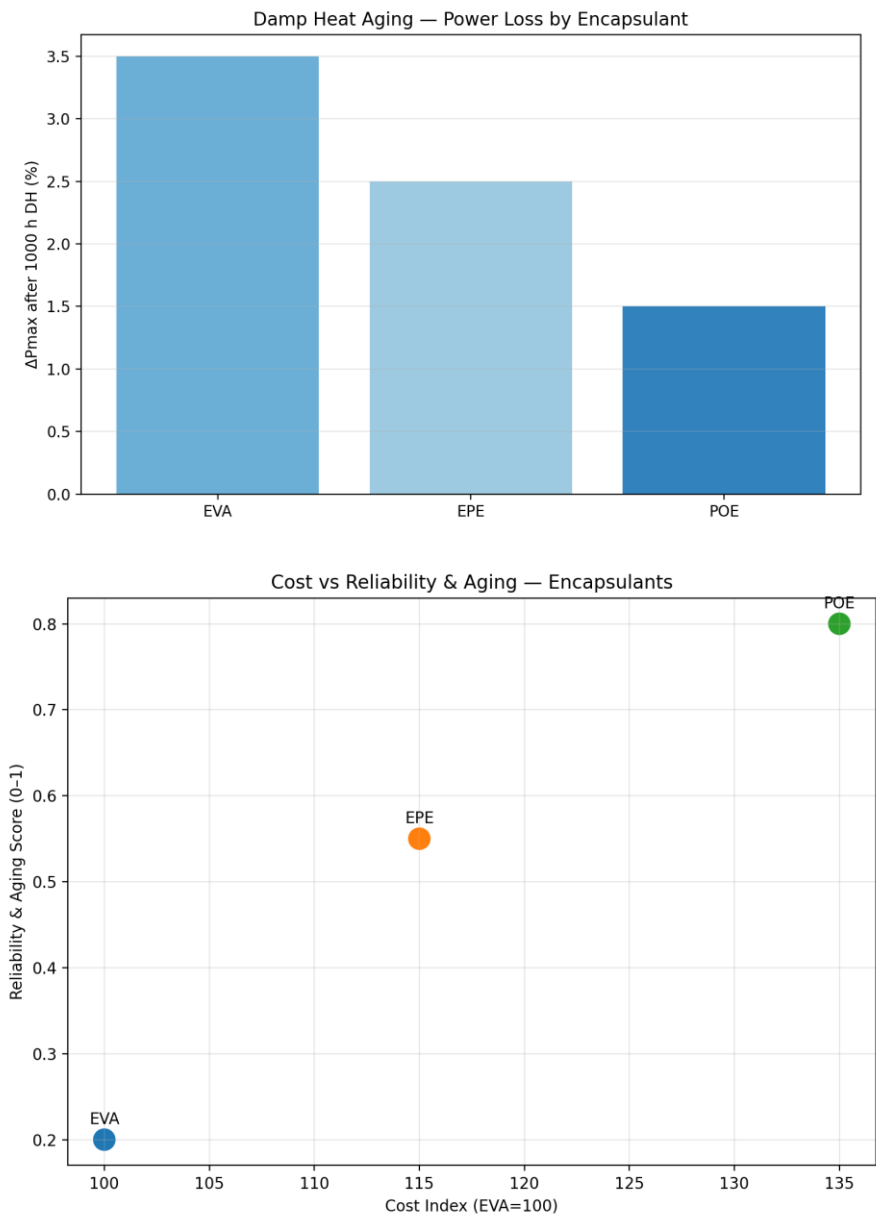
5. LCOE and Reliability (GG vs GB)

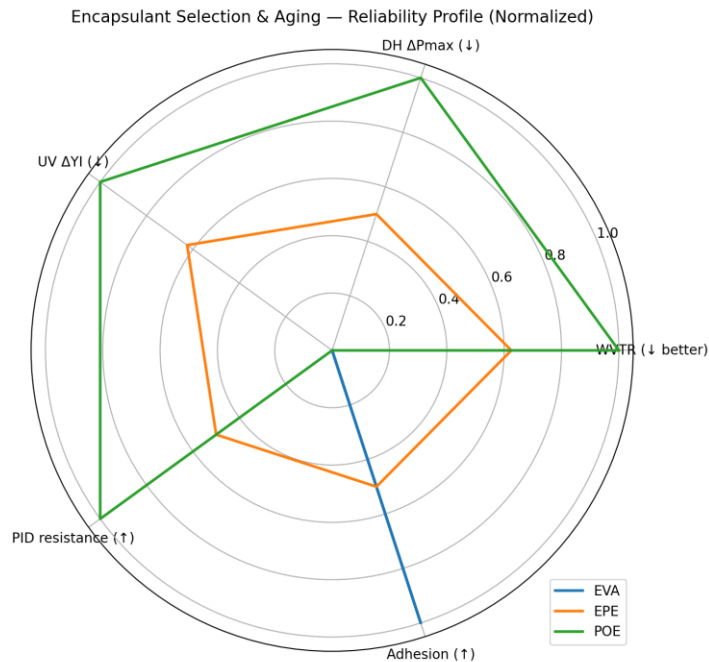
LCOE comparison under hot-site assumptions shows TOPCon minimizing LCOE owing to near-PERC cost with improved temperature and bifacial performance; HJT approaches/overcomes TOPCon where temperature and bifaciality dominate. Retained-power trajectories favor GG packages across technologies.

Technology	LCOE Ranking	Long-Term Reliability	Best Packaging
TOPCon	★ Best	★ Excellent	Glass-Glass + POE/EPE
HJT	Good (premium)	BOM-dependent	GG + POE
IBC	High (premium)	Excellent (if GG+POE)	Glass-Glass
PERC	Lowest upfront but highest LCOE	Moderate	Glass-Backsheet (EVA/EPE)

6. Encapsulant Selection and Aging

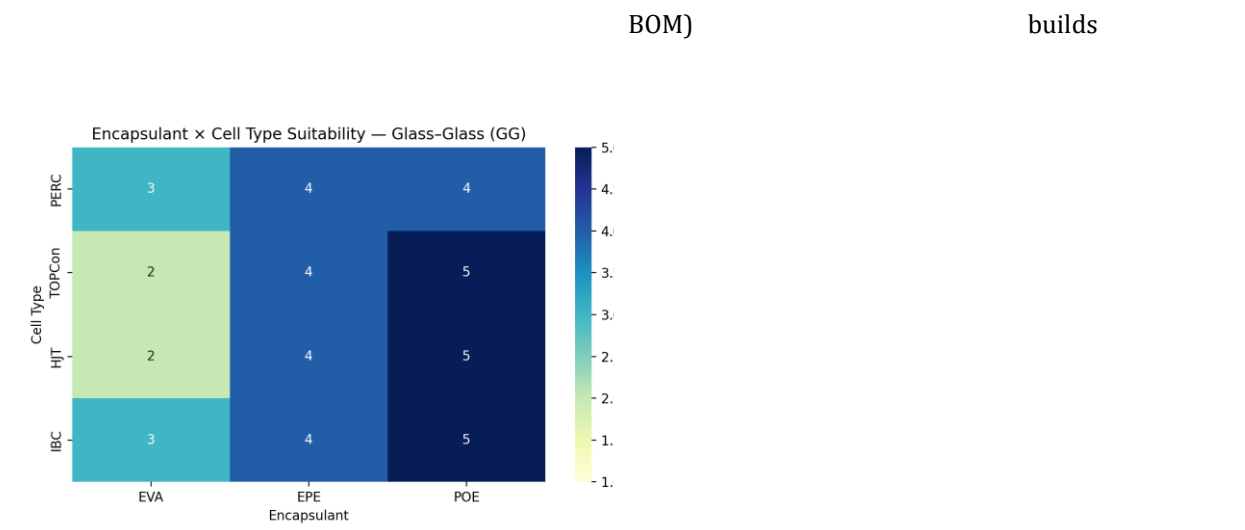
EVA: strong adhesion/clarity; moderate WVTR; acetic-acid formation under DH/UV can corrode metallization/TCO—mitigate via gel $\geq 80\%$, UV stabilizers, robust backsheets and edge seals. POE: low WVTR; no acid formation; higher electrical insulation; reduces PID and moisture risks—preferred for GG and n-type modules. EPE: co-extruded EVA-POE-EVA; balances barrier and adhesion; useful when processability with EVA outer layers is desired.





7. Encapsulant–Cell Combinations

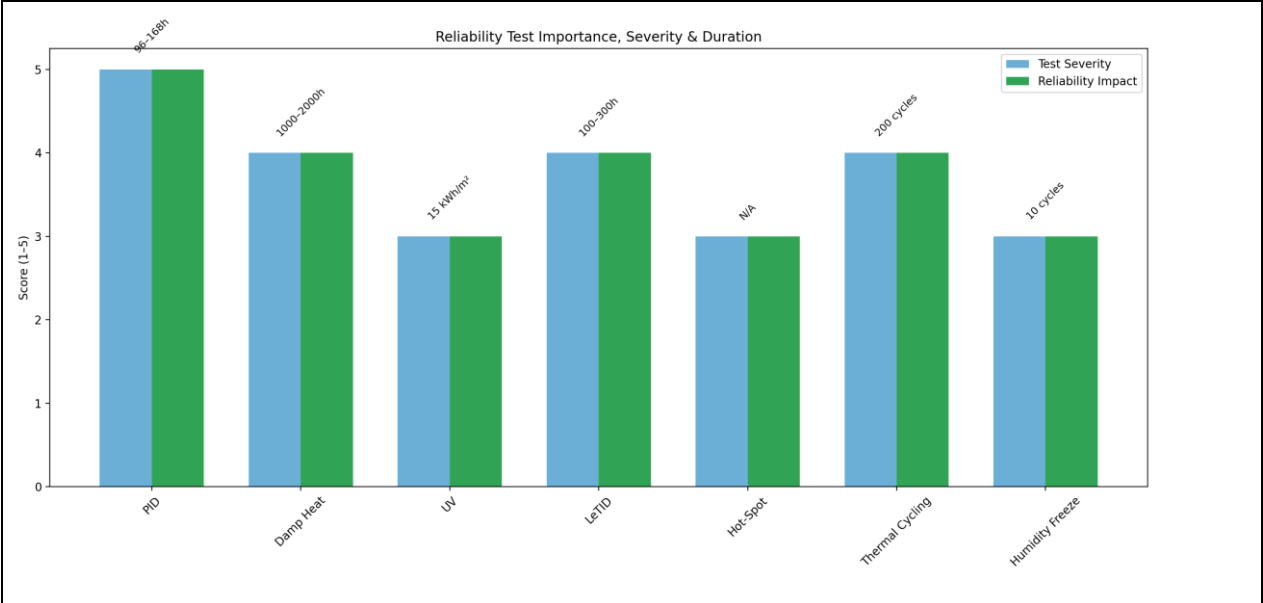
Cell Tech	EVA	EPE	POE	Notes
PERC	Viable (GB/GG), cost-leading	Improved barrier	High barrier (harsh climates)	EVA acceptable with robust backsheets; choose POE/EPE for coastal/high-volt age sites
TOPCon	Acceptable (GB)	Strong default	Preferred (GG bifacial)	POE/EPE mitigate PID/polarization and corrosion; GG benefits from low WVTR
HJT	Use with strong UV stabilization	Strong	Preferred	BOM-sensitive under DH; POE/EPE recommended
IBC	Acceptable (premium)	Strong	Preferred	Premium GG + POE common for high-efficiency



8. Reliability Test Methods and Parameters

Test	Objective		Key Parameters	Applies To	Primary Metrics	Standard	
PID	High-voltage (PID-s/p/c)	sensitivity	85°C/85% RH, ±1000 V, 96–168 h; dark & UV variants	All	ΔPmax, EL/PL, insulation resistance	IEC 62804-1:2025	TS
Damp Heat (DH)	Moisture/thermal aging		85°C/85% RH, 1000–2000 h	All	ΔPmax (<5%), EL/visual	IEC 61215	MQT 13
UVID (UV)	UV susceptibility/yellowing		15 kWh/m² @ 60–70°C	All	YI, ΔPmax	IEC 61215	MQT 10
LeTID	Light + elevated temperature degradation		1 sun @ 75–85°C, 100–300 h; current injection variants	PERC, TOPCon, some HJT	ΔPmax(t), recovery residual	IEC TS 63342; draft IEC 61215-2	
Hot-Spot	Bypass/defect robustness	heating	Partial shading; thermal imaging	All	Max cell temp, damage	IEC 61215	MQT 18

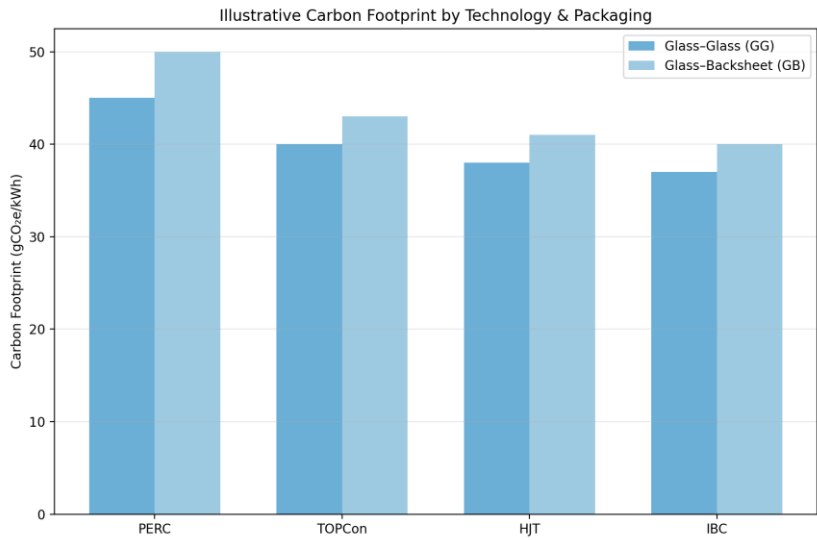
Thermal Cycling (TC)	Interconnect fatigue/microcracks		-40↔+85°C, 200 cycles	All	ΔPmax (<5%), EL	IEC MQT 11	61215
Humidity Freeze (HF)	Freeze-thaw stress	moisture	10 cycles (85/85↔-40°C)	All	ΔPmax, delamination	IEC MQT 12	61215



Test duration (text labels above each bar)

Using durations from IEC standards and industry testing:

Test	Duration / Exposure
PID	96-168 hours @ 85°C/85%RH & ±1000 V (IEC TS 62804-1:2025)
Damp Heat	1000-2000 hours @ 85°C/85%RH (IEC 61215 MQT 13)
UV	15 kWh/m² @ 60-70°C (IEC 61215 MQT 10)
LeTID	100-300 hours, 1 sun @ 75-85°C (IEC TS 63342 / MQT23 draft)
Hot-Spot	N/A (bypass diode + hotspot thermal response test)
Thermal Cycling	200 cycles from -40 → +85°C (IEC 61215 MQT 11)



9. Discussion

Results support TOPCon as the most favorable near-term LCOE choice, with HJT/IBC reserved for premium yield scenarios. Encapsulant selection measurably affects PID susceptibility and moisture-driven degradation; POE/EPE are preferred for GG bifacial and n-type modules. DH/UV outcomes emphasize BOM sensitivity,

particularly for HJT in GB structures. Market trends indicate TOPCon capacity dominance through mid-2020s with continued metallization cost reductions.

10. Conclusion

For hot/humid deployments, align cell technology and encapsulant choice to reliability test evidence: prioritize TOPCon with POE/EPE in GG bifacial designs, and apply comprehensive IEC-aligned PID/LeTID/DH/UV/TC/HF screening. This approach reduces risk, stabilizes yield, and improves bankability.

Declaration of Conflicting Interests

The authors declare no potential conflicts of interest with respect to the research, authorship and publication of this article.

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